

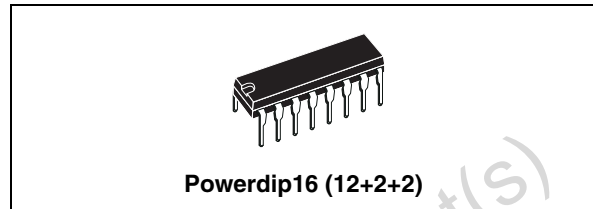
Quad Darlington switches

Features

- Four non inverting inputs with enable
- Output voltage up to 50 V
- Output current up to 1.8 A
- Very low saturation voltage
- TTL compatible inputs
- Integral fast recirculation diodes

Description

The L6220 monolithic quad Darlington switch is designed for high current, high voltage switching applications. Each of the four switches is controlled by a logic input and all four are controlled by a common inhibit input. All inputs are TTL-compatible for direct connection to logic circuits.



Each switch consists of an open-collector Darlington transistor plus a fast diode for switching applications with inductive loads. The emitters of the four switches are commoned. Any number of inputs and outputs of the same device may be paralleled.

The L6220 is mounted in a Powerdip 12 + 2 + 2 package.

Table 1. Order code

| Order code | Package |
|------------|------------|
| E-L6220 | Powerdip16 |

Figure 1. Block diagram

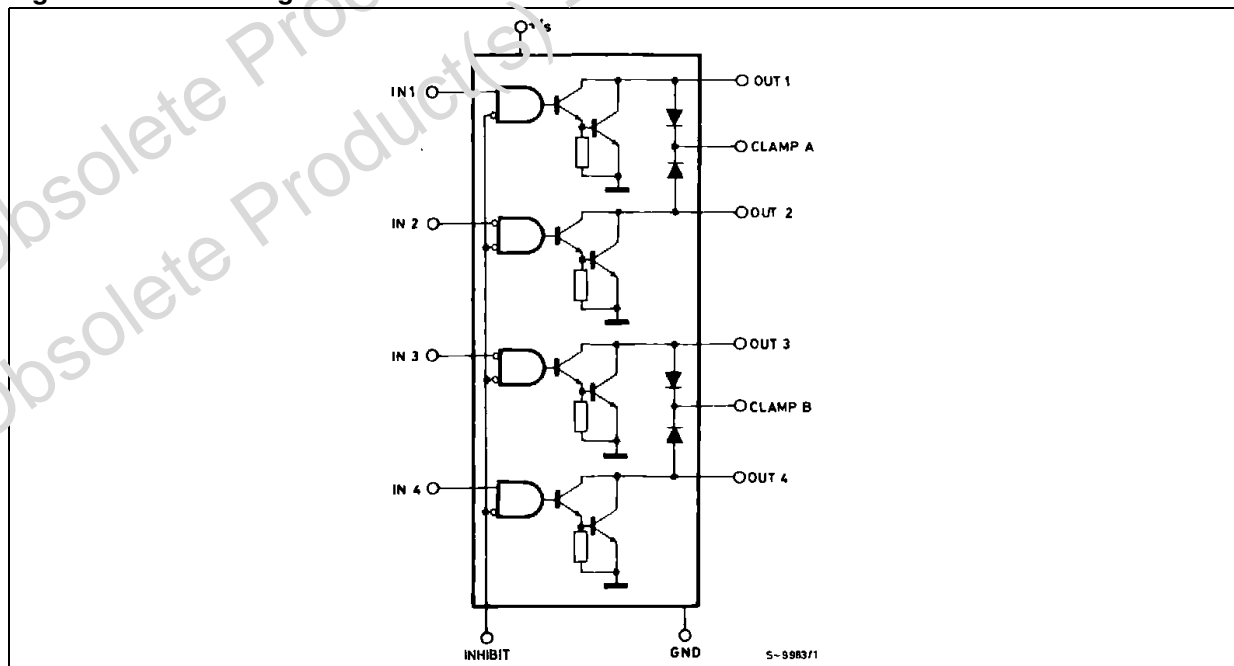
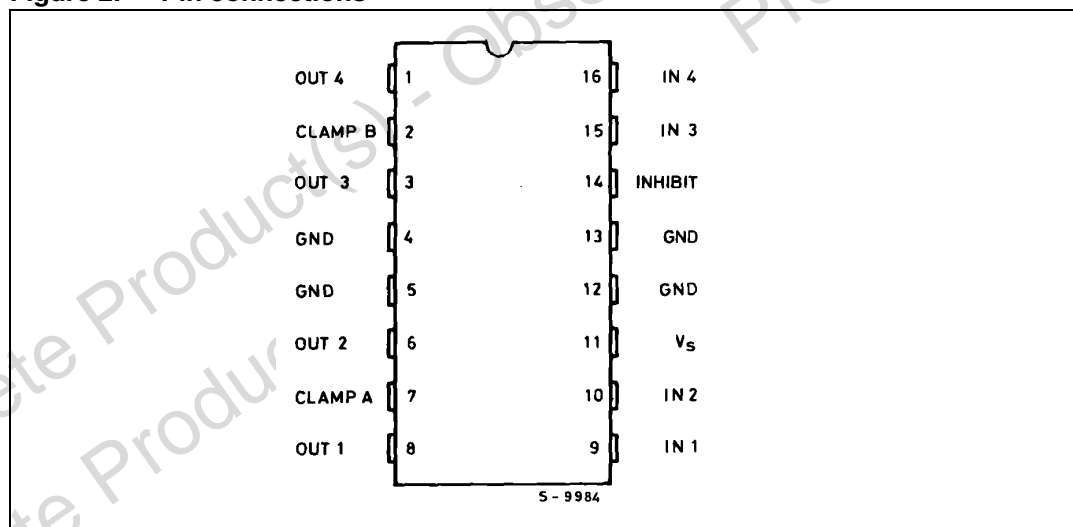


Table 2. Pin description

| Pin N# | Pin name | Function |
|--------------|----------------|--------------------------------------|
| 1 | OUT 4 | Output of driver 4 |
| 2 | CLAMP B | Diode clamp to driver 3 and driver 4 |
| 3 | OUT 3 | Output of driver 3 |
| 4, 5, 12, 13 | GND | Common ground |
| 6 | OUT 2 | Output of driver 2 |
| 7 | CLAMP A | Diode clamp to driver 1 and driver 2 |
| 8 | OUT 1 | Output of driver 1 |
| 9 | IN 1 | Input to driver 1 |
| 10 | IN 2 | Input to driver 2 |
| 11 | V _S | Logic supply voltage |
| 14 | INHIBIT | Inhibit input to all drivers |
| 15 | IN 3 | Input to driver 3 |
| 16 | IN 4 | Input to driver 4 |

Figure 2. Pin connections**Table 3. Truth table**

| Enable | Inputs 1, 4 | Power out | Enable | Inputs 2, 3 | Power out |
|--------|-------------|-----------|--------|-------------|-----------|
| L | H | ON | L | L | ON |
| L | L | OFF | L | H | OFF |
| H | X | OFF | H | X | OFF |

For each input : H = High level

L = Low level

Table 4. Absolute maximum ratings

| Symbol | Parameter | Value | Unit |
|------------------|---|---------------|--------|
| V_o | Output voltage | 50 | V |
| V_s | Logic supply voltage | 7 | V |
| V_{IN}, V_{EN} | Input voltage, enable voltage | V_s | |
| I_C | Continuous collector current (for each channel) | 1.8 | A |
| I_C | Collector peak current (repetitive, duty cycle = 10 % t_{on} = 5 ms) | 2.5 | A |
| I_C | Collector peak current (non repetitive, $t = 10 \mu s$) | 3.2 | A |
| T_{op} | Operating temperature range (junction) | - 40 to + 150 | °C |
| T_{stg} | Storage temperature range | - 55 to + 150 | °C |
| I_{sub} | Output substrate current | 350 | mA |
| P_{tot} | Total power dissipation at $T_{pins} = 90 \text{ °C}$ at $T_{amb} = 70 \text{ °C}$ | 4.3 1 | W W |

Table 5. Thermal data

| Symbol | Parameter | Value | Unit |
|------------------|--|-------|------|
| $R_{th\ j-pins}$ | Thermal resistance junction-pins max. | 14 | °C/W |
| $R_{th\ j-amb}$ | Thermal resistance junction-ambient max. | 80 | °C/W |

Table 6. Electrical characteristics

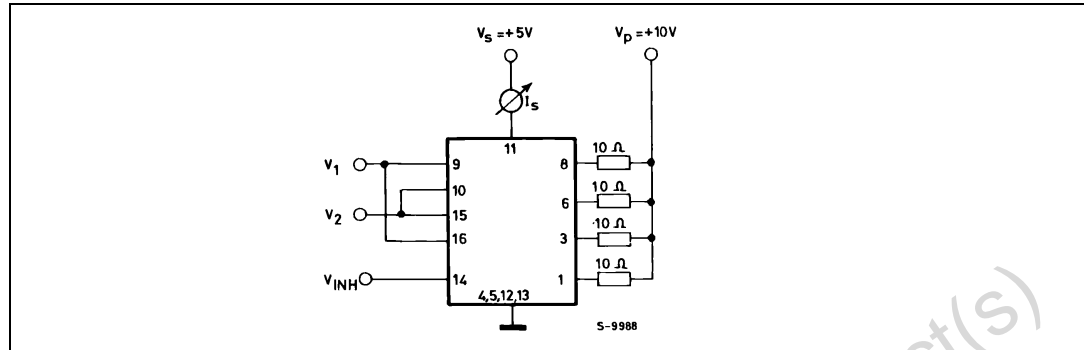
| Symbol | Parameter | Test condition | Min. | Typ. | Max. | Unit |
|---------------------|--|---|------|------|-----------------|------|
| V_s | Logic supply voltage | | 4.5 | | 5.5 | V |
| I_s | Logic supply current | All outputs ON, $I_C = 0.7 \text{ A}$ | | | 20 | mA |
| | | All outputs OFF | | | 20 | mA |
| $V_{CE(sus)}$ | Output sustaining voltage | $I_C = 100 \text{ mA}, V_{IN} = V_{INH}$ | 46 | | | V |
| I_{CEX} | Output leakage current | $V_{CE} = 50 \text{ V}, V_{IN\ 1.4} = V_{INH}$ | | | 1 | mA |
| $V_{CE(sat)}$ | Collector emitter saturation voltage (one input on ; all others inputs off.) | $V_s = 4.5 \text{ V}$ $V_{IN\ 2.3} = V_{INL}, V_{INH} = V_{INHL}$ $I_C = 0.6 \text{ A}$ $I_C = 1 \text{ A}$ $I_C = 1.8 \text{ A}$ | | | 1 1.2 1.6 | V |
| V_{INL}, V_{INHL} | Input low voltage | | | | 0.8 | V |
| I_{INL}, I_{INHL} | Input low current | $V_{IN} = V_{INL}, V_{EN} = V_{ENL}$ | | | - 100 | μA |
| V_{INH}, V_{INHH} | Input high voltage | | 2.0 | | | V |
| I_{INH}, I_{INHH} | Input high current | $V_{IN} = V_{INH}, V_{INH} = V_{INHH}$ | | | ±10 | μA |

Table 6. Electrical characteristics (continued)

| Symbol | Parameter | Test condition | Min. | Typ. | Max. | Unit |
|--------------|--------------------------------|---|------|------|------------|---------------|
| I_R | Clamp diode leakage current | $V_R = 50 \text{ V}$, $V_{INH} = V_{INH(H)}$ | | | 100 | μA |
| V_F | Clamp diode forward voltage | $I_F = 1 \text{ A}$ $I_F = 1.8 \text{ A}$ | | | 1.6 2.0 | V V |
| $t_{d(on)}$ | Turn on delay time | $V_p = 5 \text{ V}$, $R_L = 10 \Omega$ | | | 2 | μs |
| $t_{d(off)}$ | Turn off delay time | $V_p = 5 \text{ V}$, $R_L = 10 \Omega$ | | | 5 | μs |
| ΔI_s | Logic supply current variation | $V_{IN} = 5 \text{ V}$, $V_{EN} = 5 \text{ V}$ $I_{out} = -300 \text{ mA}$ for each channel | | | 120 | mA |

1 Test circuits

Figure 3. Logic supply current



Set $V_1 = 4.5\text{ V}$, $V_2 = 0.8\text{ V}$, $V_{INH} = 4.5\text{ V}$ or $V_1 = 0.8\text{ V}$, $V_2 = 4.5\text{ V}$, $V_{INH} = 0.8\text{ V}$ for I_S (all outputs off)

Set $V_1 = 2\text{ V}$, $V_2 = 0.8\text{ V}$, $V_{IN} = 0.8\text{ V}$ for I_S (all outputs on)

Figure 4. Output sustaining voltage

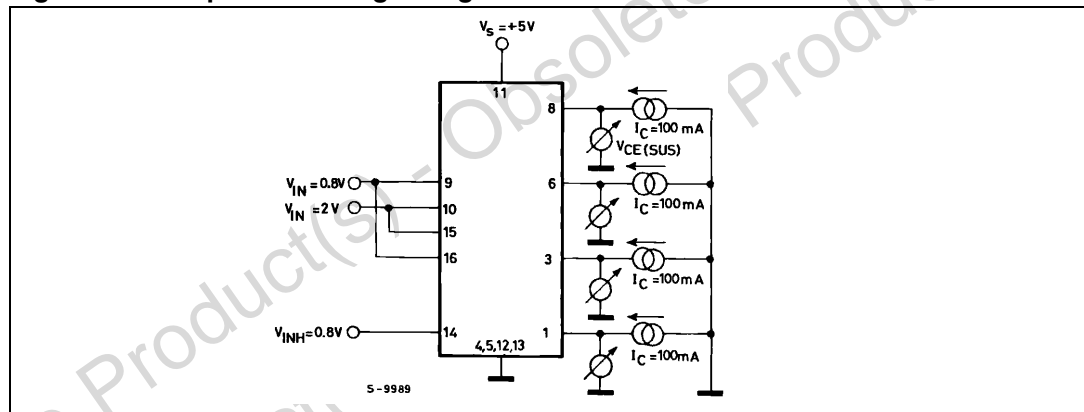


Figure 5. Output leakage current

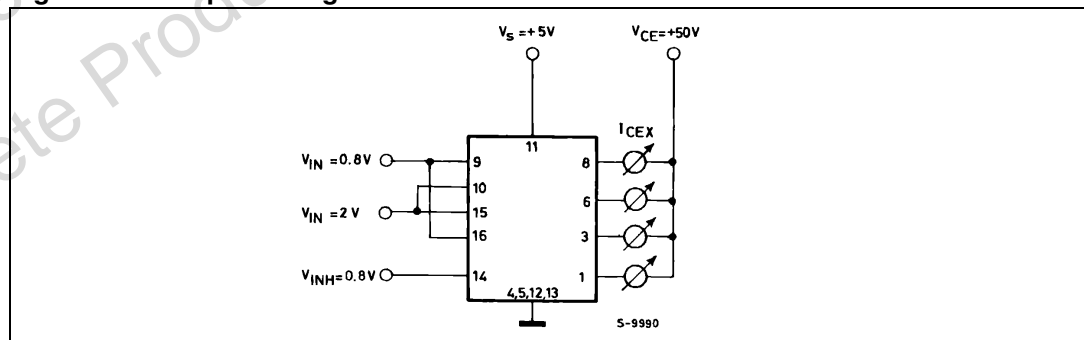


Figure 6. Collector-emitter saturation voltage

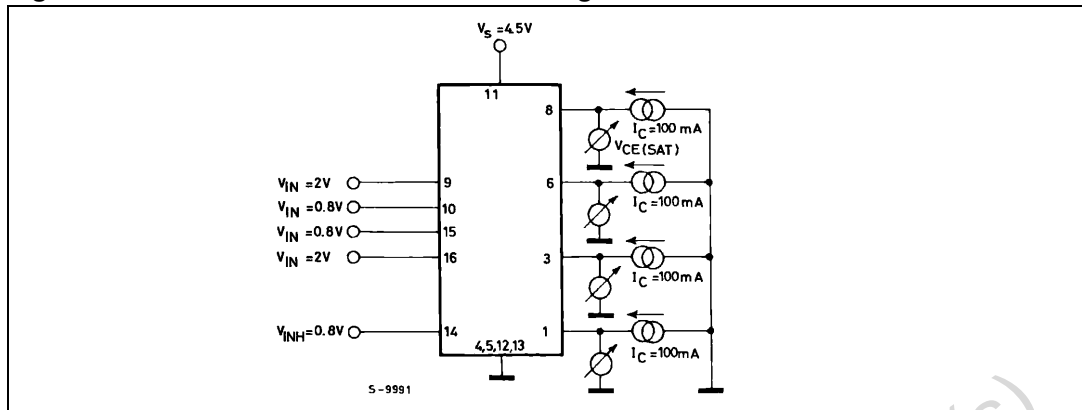
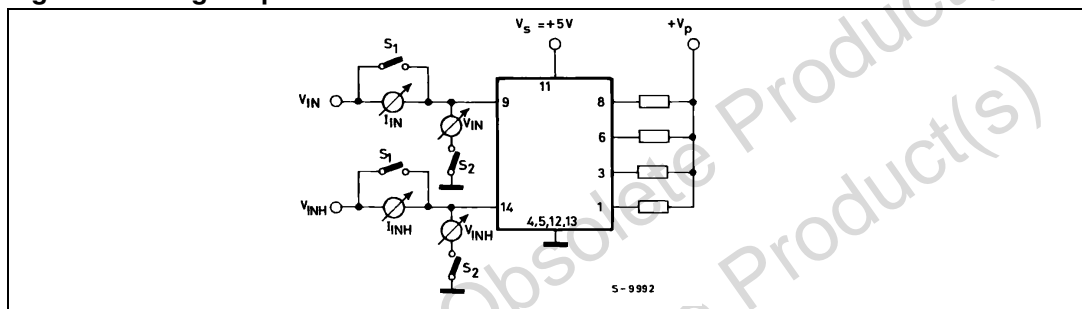


Figure 7. Logic input characteristics



- Set S_1, S_2 open, $V_{IN}, V_{INH} = 0.8\text{ V}$ for $I_{IN\ L}, I_{INH\ L}$
- Set S_1, S_2 open, $V_{IN}, V_{INH} = 2\text{ V}$ for $I_{IN\ H}, I_{INH\ H}$
- Set S_1, S_2 close, $V_{IN}, V_{INH} = 0.8\text{ V}$ for $V_{IN\ L}, V_{INH\ L}$
- Set S_1, S_2 close, $V_{IN}, V_{INH} = 2\text{ V}$ for $V_{IN\ H}, V_{INH\ H}$

Figure 8. Clamp diode leakage current.

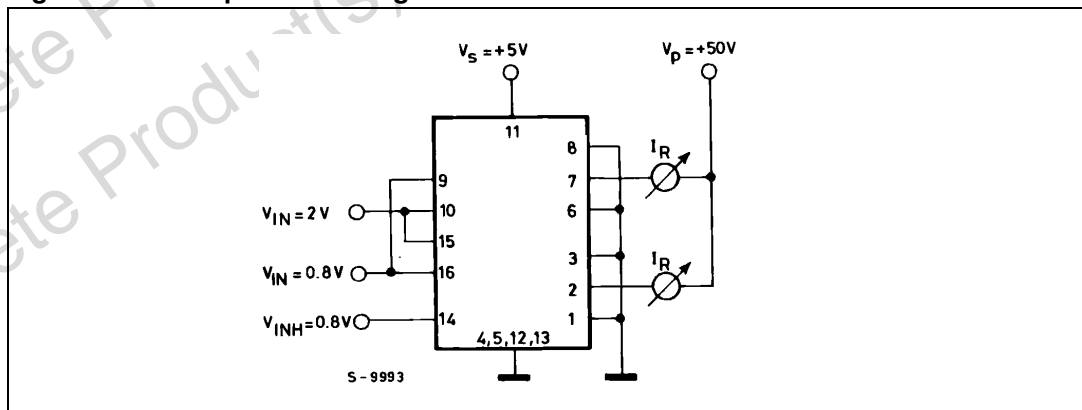


Figure 9. Clamp diode forward voltage

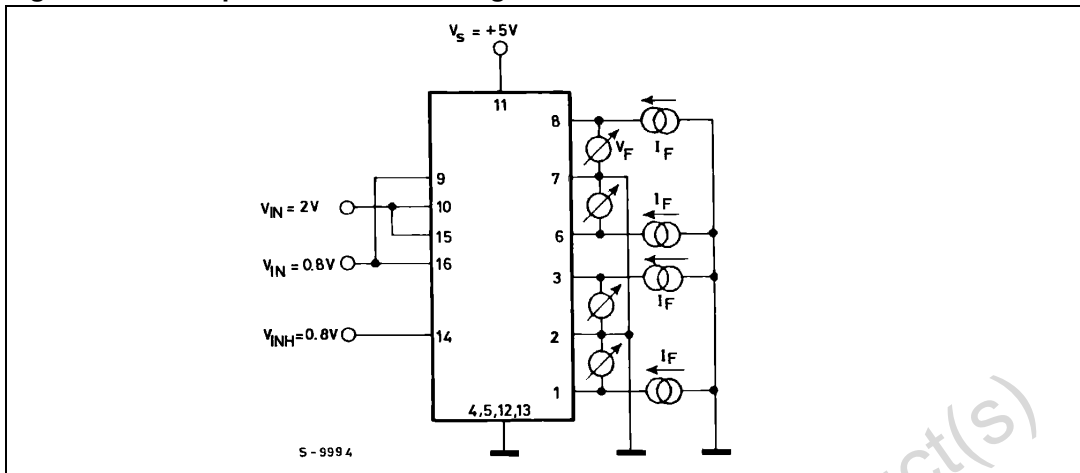


Figure 10. Switching times test circuit

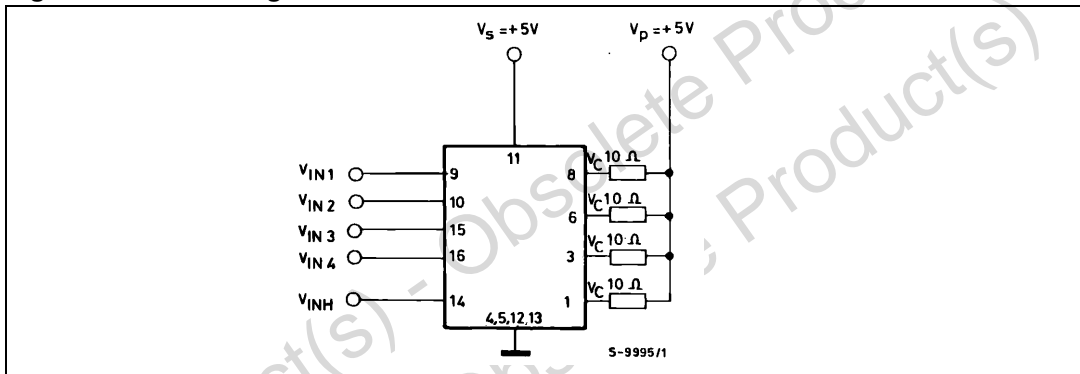


Figure 11. Switching times waveforms

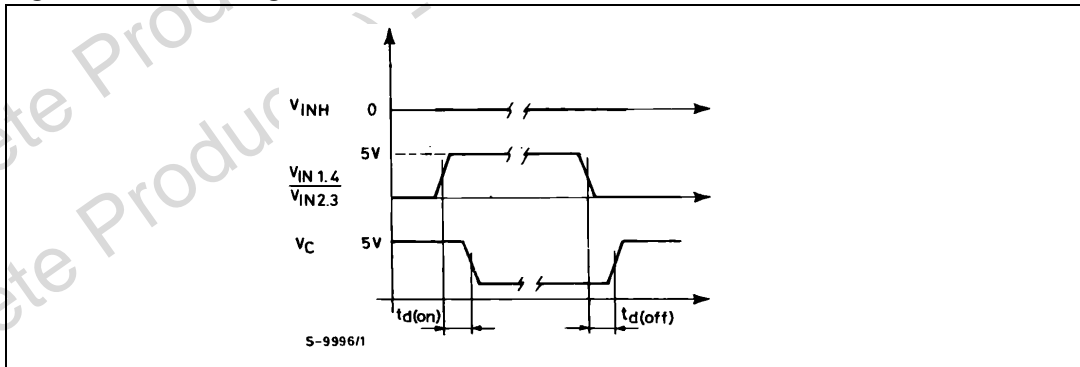


Figure 12. Collector saturation voltage versus collector current

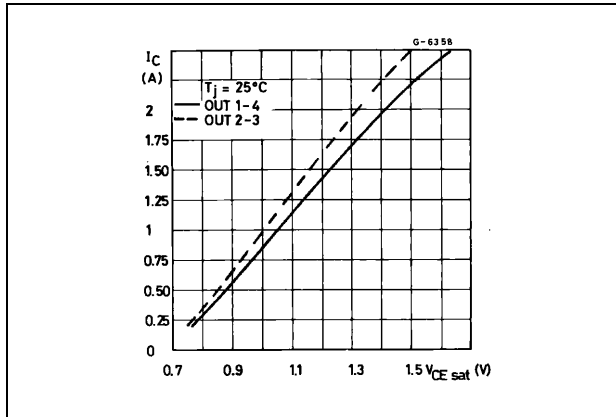


Figure 13. Free-wheeling diode forward voltage versus diode current

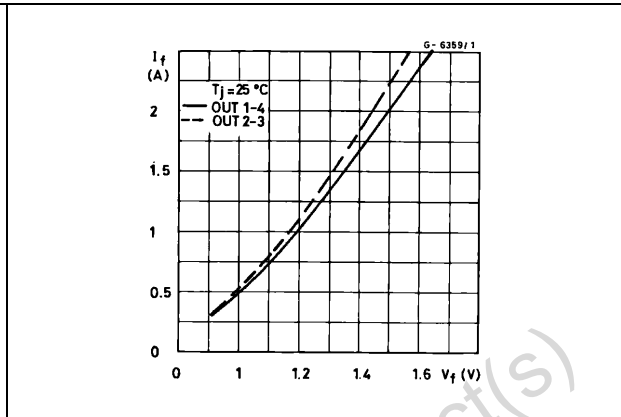


Figure 14. Collector saturation voltage versus junction temperature at $I_C = 1\text{ A}$

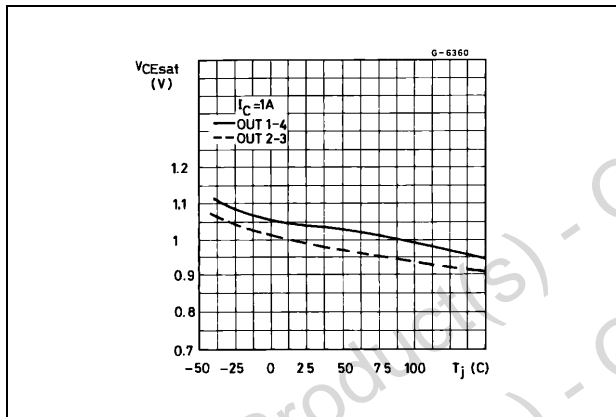


Figure 15. Free-wheeling diode forward voltage versus junction temperature at $I_f = 1\text{ A}$

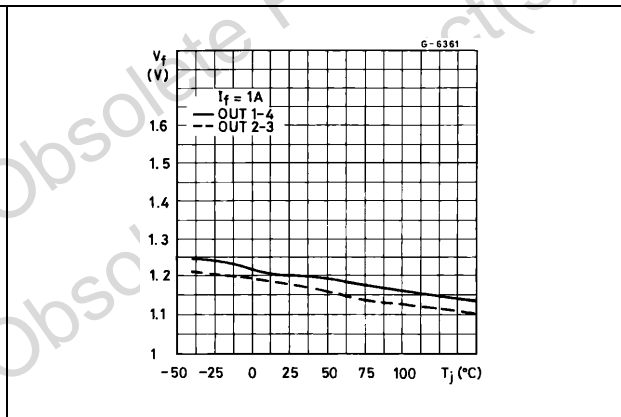


Figure 16. Collector saturation voltage versus junction temperature at $I_C = 8\text{ A}$

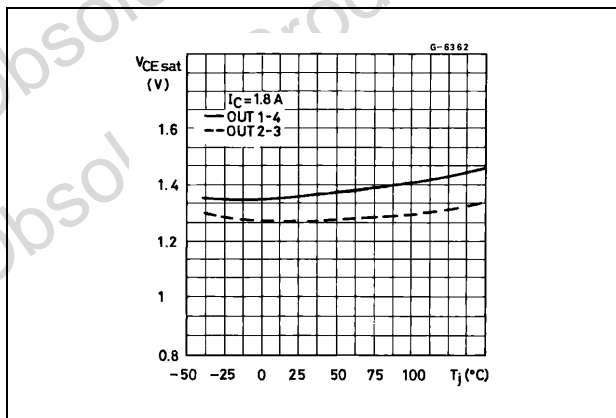
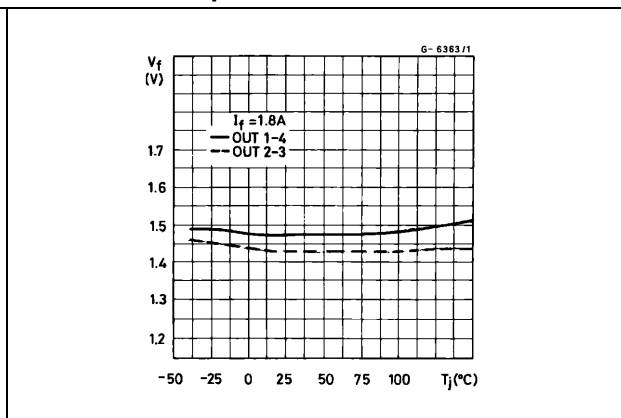


Figure 17. Free-wheeling diode forward voltage versus junction temperature at $I_f = 1\text{ A}$



2 Application information

When inductive loads are driven by L6220, a zener diode in series with the integral free-wheeling diodes increases the voltage across which energy stored in the load is discharged and therefore speeds the current decay [Figure 18](#).

Figure 18. Inductive load driver

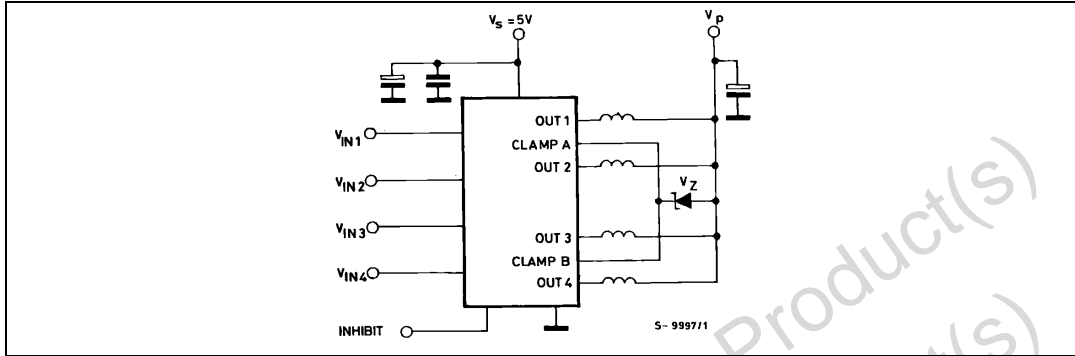
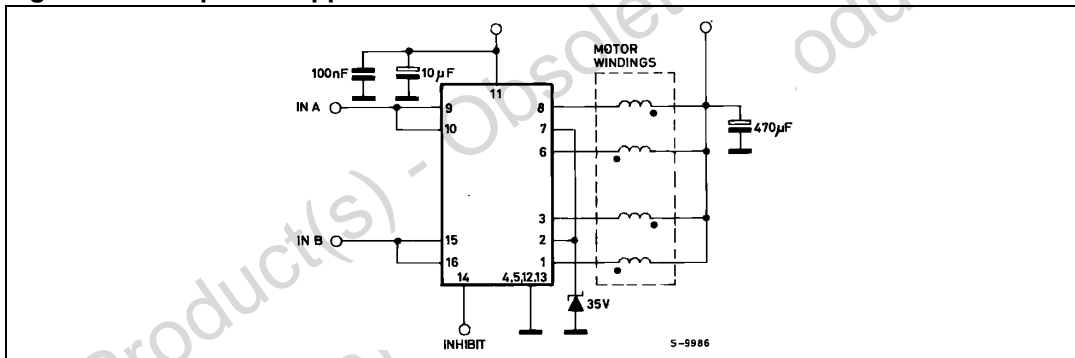


Figure 19. Unipolar stepper motor driver



For reliability it is suggested that the zener is chosen so that $V_p + V_z < 35\text{ V}$.

The reasons for this are two-fold :

1. The zener voltage changes in temperature and current.
2. The instantaneous power must be limited to avoid the reverse second breakdown.

The particular internal logic allows an easier full step driving using only two input signals.

Figure 20. Full step driving

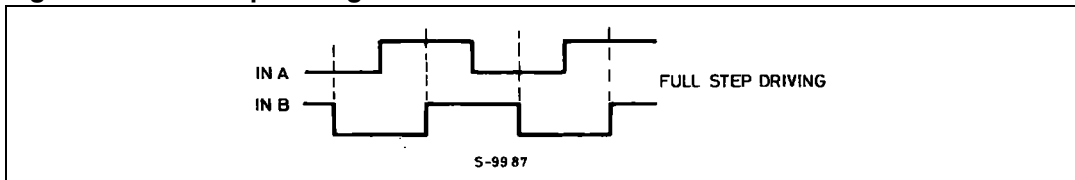
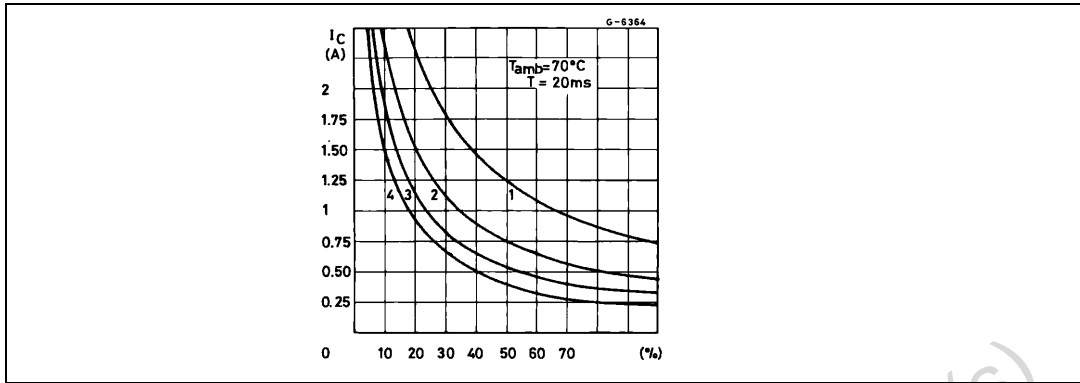


Figure 21. Allowed peak collector-current versus duty cycle for 1, 2, 3 or 4 simultaneously working outputs (L6220)



Obsolete Product(s) - Obsolete Product(s)
Obsolete Product(s) - Obsolete Product(s)

3 Mounting instructions

The $R_{th\ j-amb}$ of the L6220 can be reduced by soldering the GND pins to a suitable copper area of the printed circuit board (Figure 22) or to an external heatsink (Figure 23).

The diagram of Figure 24 shows the maximum dis-sipable power P_{tot} and the $R_{th\ j-amb}$ as a function of the side "a" of two equal square copper areas having a thickness of 35μ (1.4 mils). During soldering the pins temperature must not exceed $260\text{ }^\circ\text{C}$ and the soldering time must not be longer than 12 seconds.

The external heatsink or printed circuit copper area must be connected to electrical ground.

Figure 22. Example of P.C. board copper area which is used as heatsink

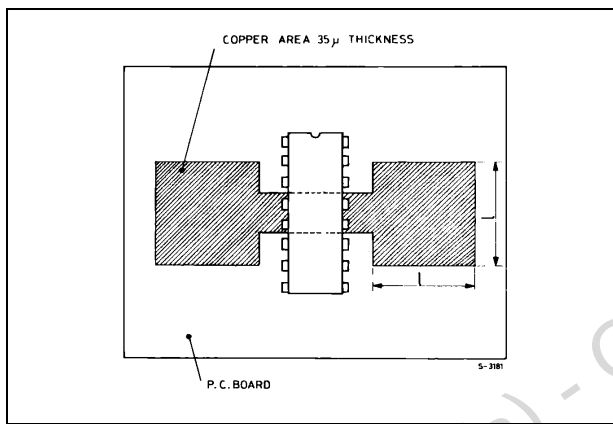


Figure 23. External heatsink mounting example

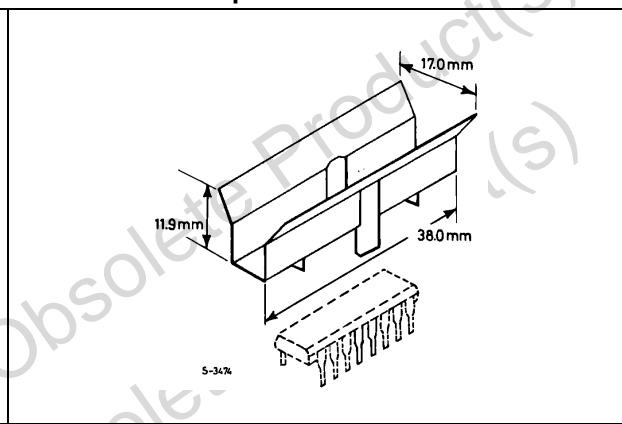


Figure 24. Maximum dissippable power and junction to ambient thermal resistance versus side "a"

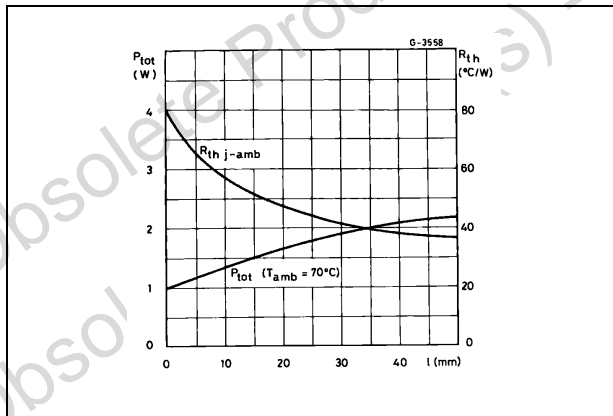


Figure 25. Maximum allowable power dissipation versus ambient temperature

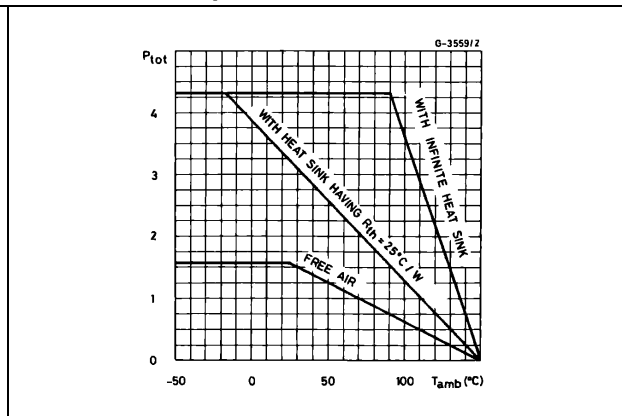
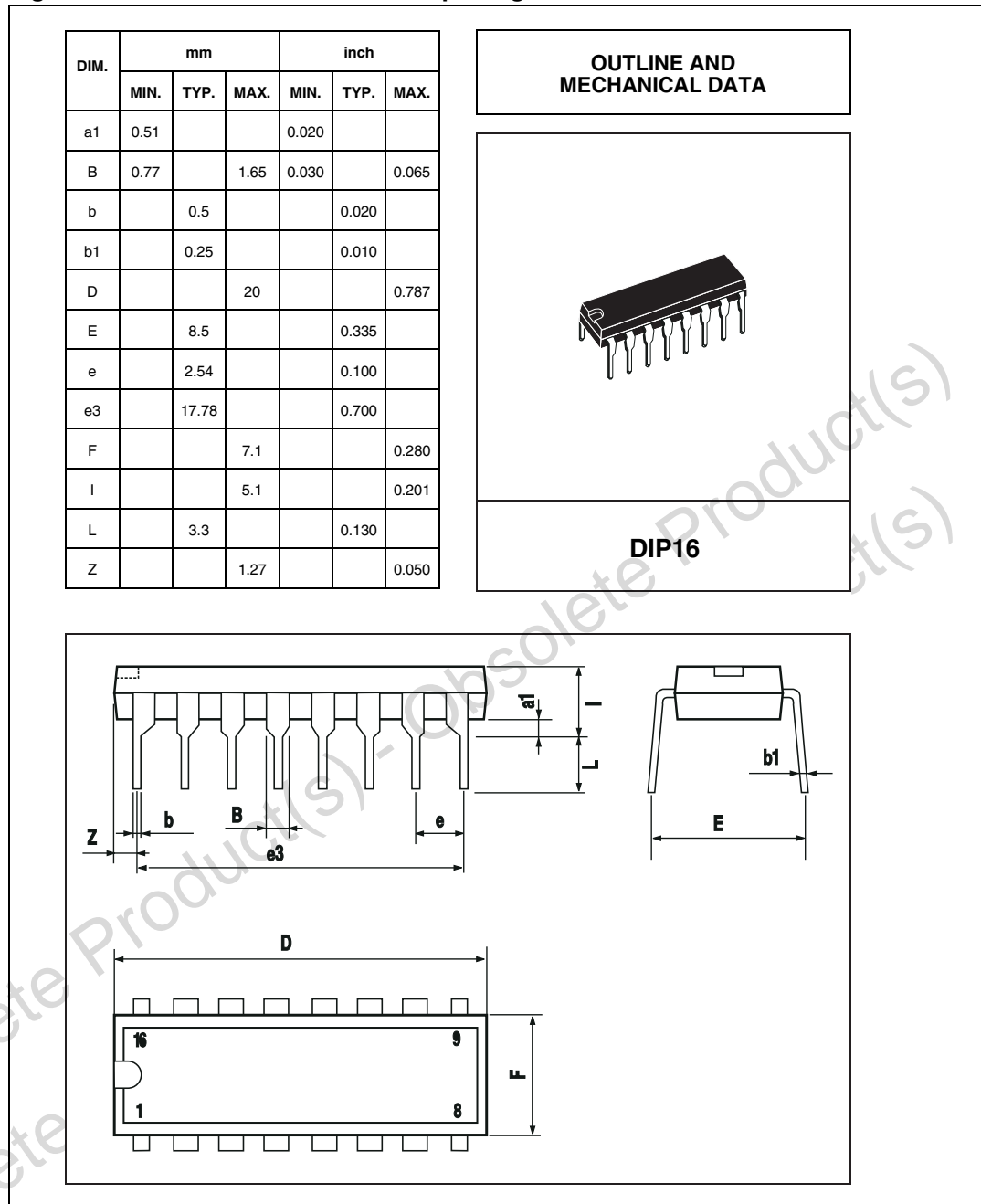


Figure 26. DIP16 mechanical data & package dimensions



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4 Revision history

Table 7. Document revision history

| Date | Revision | Description of changes |
|-------------|----------|--|
| 01-Sep-2003 | 1 | First issue |
| 01-Jul-2004 | 2 | Cancelled the L6220N part number and the relative references. Changed the style-look following the new "Corporate Technical Publications Design Guide" rules. |
| 01-Jun-2010 | 3 | Changed the order code to E-L6220 on page 1. |

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